



Final Product/Process Change Notification

Document #:FPCN22898X

Issue Date:26 Nov 2019

Title of Change:	Addition of United Microelectronics Corporation (UMC),Taiwan as wafer fabrication site.		
Proposed First Ship date:	04 Mar 2020 or earlier if approved by customer		
Contact Information:	Contact your local ON Semiconductor Sales Office or Kazunari.Kushiyama@onsemi.com		
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com>. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.		
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Yasuhiro.Igarashi@onsemi.com		
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com		
Marking of Parts/ Traceability of Change:	Laser marking lot code and lot number		
Change Category:	Wafer Fab Change		
Change Sub-Category(s):	Manufacturing Site Addition		
Sites Affected:			
ON Semiconductor Sites		External Foundry/Subcon Sites	
None		UMC, Taiwan	
Description and Purpose:			
This Final Product/Process Change Notification (FPCN) announces the addition of United Microelectronics Corporation (UMC), Taiwan as wafer fab site.			
Niigata for Back grind (BG) and Back metal (BM) process and ONSC for assembly process are not changed.			
Process	Before Change Description	After Change Description	
Wafer fab	ON Semiconductor Aizu, Japan	ON Semiconductor Aizu, Japan	United Microelectronics Corporation, Taiwan
Under Bump Metal (Metal plating for mounting)	JX Nippon Mining & Metals Corporation, Japan	JX Nippon Mining & Metals Corporation, Japan	
There is no product marking change as a result of this change.			

**Reliability Data Summary:**QV DEVICE NAME: EFC2K103NUZTDGRMS : S50064PACKAGE : WLCSP10

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 80% max rated V	1,008 hrs	0/231
HTGB	JESD22-A108	Ta=150°C, 100% max rated Vgss	1,008 hrs	0/231
HTSL	JESD22-A103	Ta=150°C	1,008 hrs	0/231
LTSL	JESD22-A119	Ta=-55°C	1,008 hrs	0/231
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15,000 cyc	0/231
TC	JESD22-A104	Ta= -40°C to +125°C	1,000 cyc	0/231
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
EFC2K103NUZTDG	EFC2K103NUZTDG
EFC2K102NUZTDG	EFC2K103NUZTDG



Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
EFC2K103NUZTDG		EFC2K103NUZTDG		